



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



Advanced PMU for Samsung S3C6410

FEATURES

- Optimized for Samsung S3C6410 Processor
- Three Step-Down DC/DC Converters
- Four Low-Dropout Linear Regulators
- I²C™ Serial Interface
- Advanced Enable/Disable Sequencing Controller
- Minimal External Components
- Tiny 4x4mm TQFN44-32 Package
 - 0.75mm Package Height
 - Pb-Free and RoHS Compliant

GENERAL DESCRIPTION

The ACT8896 is a complete, cost effective, highly-efficient *ActivePMU™* power management solution, optimized for the unique power, voltage-sequencing, and control requirements of the Samsung S3C6410 processor.

This device features three step-down DC/DC converters and four low-noise, low-dropout linear regulators.

The three DC/DC converters utilize a high-efficiency, fixed-frequency (2MHz), current-mode PWM control architecture that requires a minimum number of external components. Two DC/DCs are capable of supplying up to 900mA of output current, while the third supports up to 700mA. All four low-dropout linear regulators are high-performance, low-noise, regulators that supply up to 150mA, 150mA, 250mA, and 250mA, respectively.

The ACT8896 is available in a compact, Pb-Free and RoHS-compliant TQFN44-32 package.

TYPICAL APPLICATION DIAGRAM

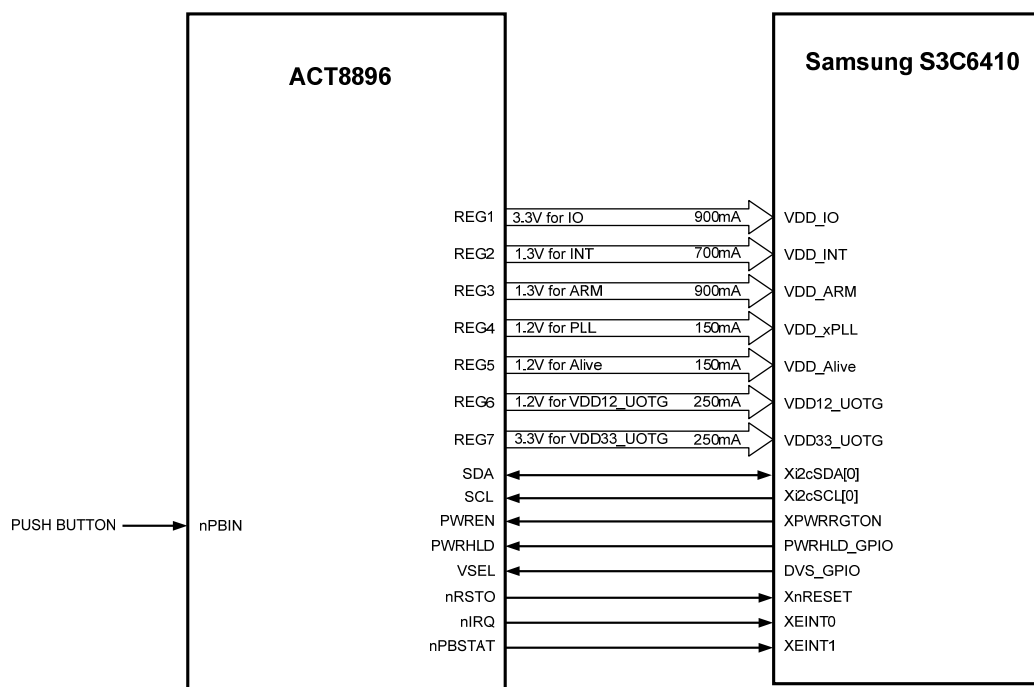
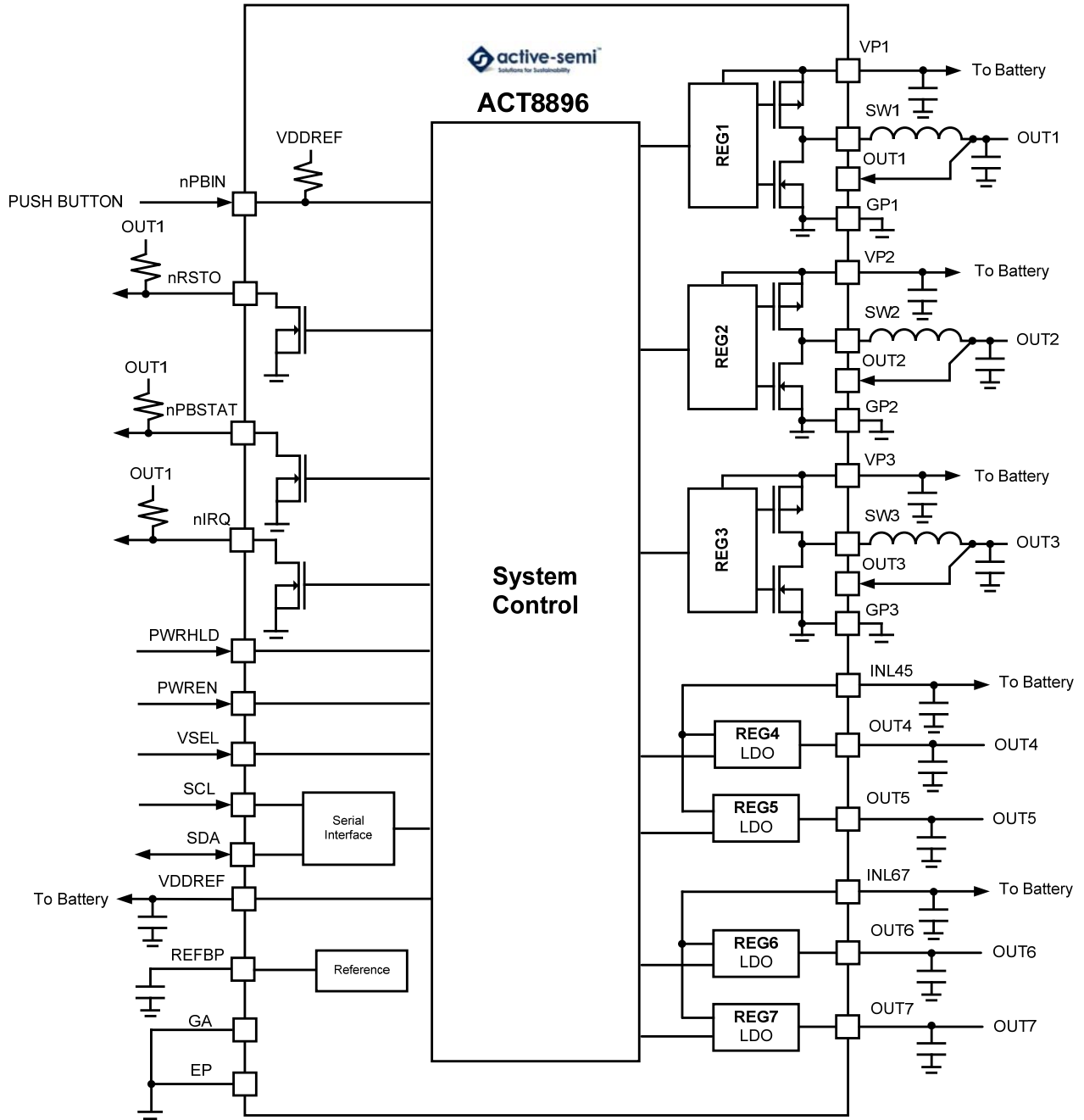


TABLE OF CONTENTS

General Information	p. 01
Functional Block Diagram	p. 03
Ordering Information	p. 04
Pin Configuration	p. 04
Pin Descriptions	p. 05
Absolute Maximum Ratings	p. 07
I ² C Interface Electrical Characteristics	p. 08
Global Register Map	p. 09
Register and Bit Descriptions	p. 10
System Control Electrical Characteristics	p. 13
Step-Down DC/DC Electrical Characteristics	p. 14
Low-Noise LDO Electrical Characteristics	p. 15
Typical Performance Characteristics	p. 16
System control information	p. 21
Interfacing with the Samsung S3C6410	p. 21
Control Signals	p. 22
Push-Button Control	p. 23
Control Sequences	p. 23
Functional Description	p. 25
I ² C Interface	p. 25
Voltage Monitor and Interrupt	p. 25
Thermal Shutdown	p. 25
Step-Down DC/DC Regulators	p. 26
General Description	p. 26
100% Duty Cycle Operation	p. 26
Synchronous Rectification	p. 26
Soft-Start	p. 26
Compensation	p. 26
Configuration Options	p. 26
OK[] and Output Fault Interrupt	p. 27
PCB Layout Considerations	p. 27
Low-Noise, Low-Dropout Linear Regulators	p. 28
General Description	p. 28
Output Current Limit	p. 28
Compensation	p. 28
Configuration Options	p. 28
OK[] and Output Fault Interrupt	p. 28
PCB Layout Considerations	p. 28
TQFN44-32 Package Outline and Dimensions	p. 30

FUNCTIONAL BLOCK DIAGRAM



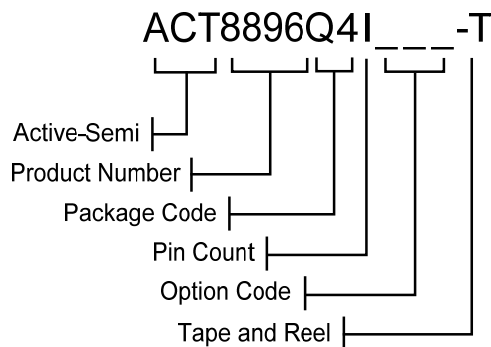
ORDERING INFORMATION^{①②}

PART NUMBER	V _{OUT1} /V _{STBY1} ^③	V _{OUT2} /V _{STBY2}	V _{OUT3} /V _{STBY3}	V _{OUT4}	V _{OUT5}	V _{OUT6}	V _{OUT7}	PACKAGE	PINS	TEMPERATURE RANGE
ACT8896Q4I133-T	3.3V/3.3V	1.3V/1.3V	1.3V/1.3V	1.2V	1.2V	1.2V	3.3V	TQFN44-32	32	-40°C to +85°C

①: All Active-Semi components are RoHS Compliant and with Pb-free plating unless specified differently. The term Pb-free means semiconductor products that are in compliance with current RoHS (Restriction of Hazardous Substances) standards.

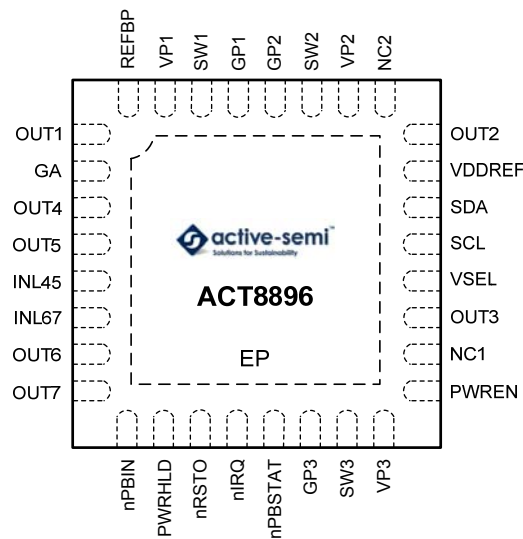
②: Standard product options are identified in this table. Contact factory for custom options, minimum order quantity is 12,000 units.

③: To select V_{STBYx} as a output regulation voltage of REGx, drive VSEL to a logic high. The V_{STBYx} can be set by software via I²C interface, refer to appropriate sections of this datasheet for V_{STBYx} setting.



PIN CONFIGURATION

TOP VIEW



Thin - QFN (TQFN44-32)

PIN DESCRIPTIONS

PIN	NAME	DESCRIPTION
1	OUT1	Output Feedback Sense for REG1. Connect this pin directly to the output node to connect the internal feedback network to the output voltage.
2	GA	Analog Ground. Connect GA directly to a quiet ground node. Connect GA, GP1, GP2 and GP3 together at a single point as close to the IC as possible.
3	OUT4	Output Voltage for REG4. Capable of delivering up to 150mA of output current. Connect a 1.5µF ceramic capacitor from OUT4 to GA. The output is discharged to GA with 1.5kΩ resistor when disabled.
4	OUT5	Output Voltage for REG5. Capable of delivering up to 150mA of output current. Connect a 1.5µF ceramic capacitor from OUT5 to GA. The output is discharged to GA with 1.5kΩ resistor when disabled.
5	INL45	Power Input for REG4 and REG5. Bypass to GA with a high quality ceramic capacitor placed as close to the IC as possible.
6	INL67	Power Input for REG6 and REG7. Bypass to GA with a high quality ceramic capacitor placed as close to the IC as possible.
7	OUT6	Output Voltage for REG6. Capable of delivering up to 250mA of output current. Connect a 2.2µF ceramic capacitor from OUT6 to GA. The output is discharged to GA with 1.5kΩ resistor when disabled.
8	OUT7	Output Voltage for REG7. Capable of delivering up to 250mA of output current. Connect a 2.2µF ceramic capacitor from OUT7 to GA. The output is discharged to GA with 1.5kΩ resistor when disabled.
9	nPBIN	Master Enable Input. Drive nPBIN to GA through a 50kΩ resistor to enable the IC, drive nPBIN directly to GA to assert a Hard-Reset condition. Refer to the <i>nPBIN Multi-Function Input</i> section for more information. nPBIN is internally pulled up to V _{VDDREF} through a 35kΩ resistor.
10	PWRHLD	Power Hold Input. Refer to the <i>Control Sequences</i> section for more information.
11	nRSTO	Active Low Reset Output. See the <i>nRSTO Output</i> section for more information.
12	nIRQ	Open-Drain Interrupt Output. nIRQ asserts any time an unmasked fault condition exists or an interrupt occurs. See the <i>nIRQ Output</i> section for more information.
13	nPBSTAT	Active-Low Open-Drain Push-Button Status Output. nPBSTAT is asserted low whenever the nPBIN is pushed, and is high-Z otherwise. See the <i>nPBSTAT Output</i> section for more information.
14	GP3	Power Ground for REG3. Connect GA, GP1, GP2, and GP3 together at a single point as close to the IC as possible.
15	SW3	Switching Node Output for REG3. Connect this pin to the switching end of the inductor.
16	VP3	Power Input for REG3. Bypass to GP3 with a high quality ceramic capacitor placed as close to the IC as possible.
17	PWREN	Power Enable Input. Refer to the <i>Control Sequences</i> section for more information.
18	NC1	Not Connected. Not internally connected.
19	OUT3	Output Feedback Sense for REG3. Connect this pin directly to the output node to connect the internal feedback network to the output voltage.
20	VSEL	Step-Down DC/DCs Output Voltage Selection. Drive to logic low to select default output voltage. Drive to logic high to select secondary output voltage. See the <i>Output Voltage Programming</i> section for more information.
21	SCL	Clock Input for I ² C Serial Interface.
22	SDA	Data Input for I ² C Serial Interface. Data is read on the rising edge of SCL.

PIN DESCRIPTIONS CONT'D

PIN	NAME	DESCRIPTION
23	VDDREF	Power supply for the internal reference. Connect this pin directly to the system power supply. Bypass VDDREF to GA with a 1 μ F capacitor placed as close to the IC as possible. Star connection with VP1, VP2 and VP3 preferred.
24	OUT2	Output Feedback Sense for REG2. Connect this pin directly to the output node to connect the internal feedback network to the output voltage.
25	NC2	Not Connected. Not internally connected.
26	VP2	Power Input for REG2 and System Control. Bypass to GP2 with a high quality ceramic capacitor placed as close to the IC as possible.
27	SW2	Switching Node Output for REG2. Connect this pin to the switching end of the inductor.
28	GP2	Power Ground for REG2. Connect GA, GP1, GP2 and GP3 together at a single point as close to the IC as possible.
29	GP1	Power Ground for REG1. Connect GA, GP1, GP2 and GP3 together at a single point as close to the IC as possible.
30	SW1	Switching Node Output for REG1. Connect this pin to the switching end of the inductor.
31	VP1	Power Input for REG1. Bypass to GP1 with a high quality ceramic capacitor placed as close to the IC as possible.
32	REFBP	Reference Bypass. Connect a 0.047 μ F ceramic capacitor from REFBP to GA. This pin is discharged to GA in shutdown.
EP	EP	Exposed Pad. Must be soldered to ground on PCB.

ABSOLUTE MAXIMUM RATINGS^①

PARAMETER	VALUE	UNIT
VP1 to GP1, VP2 to GP2, VP3 to GP3	-0.3 to + 6	V
INL, VDDREF to GA	-0.3 to + 6	V
nPBIN, SCL, SDA, REFBP, PWRHLD, PWREN, VSEL to GA	-0.3 to ($V_{VDDREF} + 0.3$)	V
nRSTO, nIRQ, nPBSTAT to GA	-0.3 to + 6	V
SW1, OUT1 to GP1	-0.3 to ($V_{VP1} + 0.3$)	V
SW2, OUT2 to GP2	-0.3 to ($V_{VP2} + 0.3$)	V
SW3, OUT3 to GP3	-0.3 to ($V_{VP3} + 0.3$)	V
OUT4, OUT5, OUT6, OUT7 to GA	-0.3 to ($V_{INL} + 0.3$)	V
GP1, GP2, GP3 to GA	-0.3 to + 0.3	V
Junction to Ambient Thermal Resistance (θ_{JA})	27.5	°C/W
Operating Ambient Temperature	-40 to 85	°C
Maximum Junction Temperature	125	°C
Storage Temperature	-65 to 150	°C
Lead Temperature (Soldering, 10 sec)	300	°C

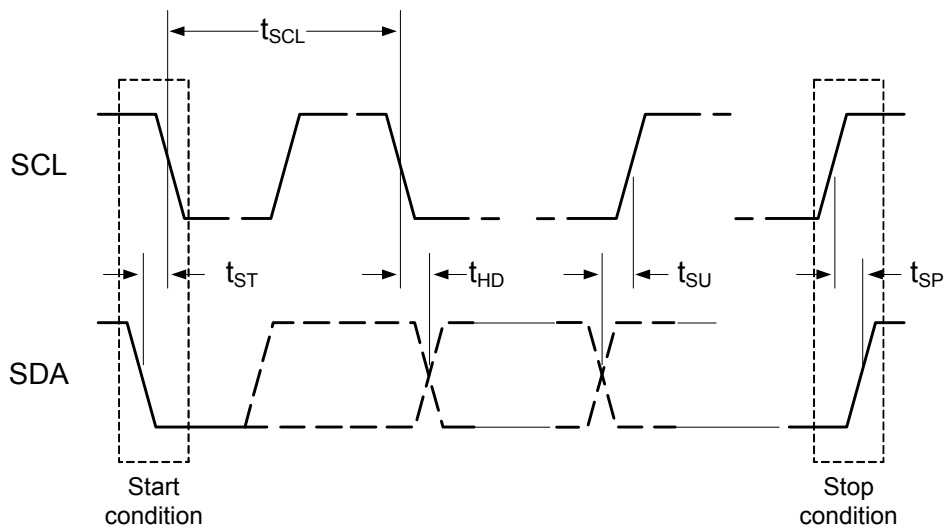
①: Do not exceed these limits to prevent damage to the device. Exposure to absolute maximum rating conditions for long periods may affect device reliability.

I²C INTERFACE ELECTRICAL CHARACTERISTICS

($V_{VP1} = V_{VP2} = V_{VP3} = 3.6V$, $T_A = 25^\circ C$, unless otherwise specified.)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
SCL, SDA Input Low	$V_{VDDREF} = 3.1V$ to $5.5V$, $T_A = -40^\circ C$ to $85^\circ C$			0.35	V
SCL, SDA Input High	$V_{VDDREF} = 3.1V$ to $5.5V$, $T_A = -40^\circ C$ to $85^\circ C$	1.55			V
SDA Leakage Current				1	μA
SCL Leakage Current			1	2	μA
SDA Output Low	$I_{OL} = 5mA$			0.35	V
SCL Clock Period, t_{SCL}		1.5			μs
SDA Data Setup Time, t_{SU}		100			ns
SDA Data Hold Time, t_{HD}		300			ns
Start Setup Time, t_{ST}	For Start Condition	100			ns
Stop Setup Time, t_{SP}	For Stop Condition	100			ns

Figure 1:
I²C Compatible Serial Bus Timing



GLOBAL REGISTER MAP

OUTPUT	ADDRESS		BITS							
			D7	D6	D5	D4	D3	D2	D1	D0
SYS	0x00	NAME	TRST	nSYSMODE	nSYSLEVMSK	nSYSSTAT	SYSLEV[3]	SYSLEV[2]	SYSLEV[1]	SYSLEV[0]
		DEFAULT ^①	0	1	0	R	0	1	1	1
SYS	0x01	NAME	Reserved	Reserved	Reserved	Reserved	SCRATCH	SCRATCH	SCRATCH	SCRATCH
		DEFAULT ^①	0	0	0	0	0	0	0	0
REG1	0x20	NAME	Reserved	Reserved	VSET1[5]	VSET1[4]	VSET1[3]	VSET1[2]	VSET1[1]	VSET1[0]
		DEFAULT ^①	0	0	1	1	1	0	0	1
REG1	0x21	NAME	Reserved	Reserved	VSET2[5]	VSET2[4]	VSET2[3]	VSET2[2]	VSET2[1]	VSET2[0]
		DEFAULT ^①	0	0	1	1	1	0	0	1
REG1	0x22	NAME	ON	PHASE	MODE	DELAY[2] ^②	DELAY[1] ^②	DELAY[0] ^②	nFLTMSK	OK
		DEFAULT ^①	0	0	0	0	0	0	0	R
REG2	0x30	NAME	Reserved	Reserved	VSET1[5]	VSET1[4]	VSET1[3]	VSET1[2]	VSET1[1]	VSET1[0]
		DEFAULT ^①	0	0	0	1	1	0	1	0
REG2	0x31	NAME	Reserved	Reserved	VSET2[5]	VSET2[4]	VSET2[3]	VSET2[2]	VSET2[1]	VSET2[0]
		DEFAULT ^①	0	0	0	1	1	0	1	0
REG2	0x32	NAME	ON	PHASE	MODE	DELAY[2] ^②	DELAY[1] ^②	DELAY[0] ^②	nFLTMSK	OK
		DEFAULT ^①	0	0	0	0	0	0	0	R
REG3	0x40	NAME	Reserved	Reserved	VSET1[5]	VSET1[4]	VSET1[3]	VSET1[2]	VSET1[1]	VSET1[0]
		DEFAULT ^①	0	0	0	1	1	0	1	0
REG3	0x41	NAME	Reserved	Reserved	VSET2[5]	VSET2[4]	VSET2[3]	VSET2[2]	VSET2[1]	VSET2[0]
		DEFAULT ^①	0	0	0	1	1	0	1	0
REG3	0x42	NAME	ON	PWRSTAT	MODE	DELAY[2] ^②	DELAY[1] ^②	DELAY[0] ^②	nFLTMSK	OK
		DEFAULT ^①	0	0	0	0	0	0	0	R
REG4	0x50	NAME	Reserved	Reserved	VSET[5]	VSET[4]	VSET[3]	VSET[2]	VSET[1]	VSET[0]
		DEFAULT ^①	0	0	0	1	1	0	0	0
REG4	0x51	NAME	ON	DIS	LOWIQ	DELAY[2] ^②	DELAY[1] ^②	DELAY[0] ^②	nFLTMSK	OK
		DEFAULT ^①	0	1	0	0	0	0	0	R
REG5	0x54	NAME	Reserved	Reserved	VSET[5]	VSET[4]	VSET[3]	VSET[2]	VSET[1]	VSET[0]
		DEFAULT ^①	0	0	0	1	1	0	0	0
REG5	0x55	NAME	ON	DIS	LOWIQ	DELAY[2] ^②	DELAY[1] ^②	DELAY[0] ^②	nFLTMSK	OK
		DEFAULT ^①	0	1	0	0	0	0	0	R
REG6	0x60	NAME	Reserved	Reserved	VSET[5]	VSET[4]	VSET[3]	VSET[2]	VSET[1]	VSET[0]
		DEFAULT ^①	0	0	0	1	1	0	0	0
REG6	0x61	NAME	ON	DIS	LOWIQ	DELAY[2] ^②	DELAY[1] ^②	DELAY[0] ^②	nFLTMSK	OK
		DEFAULT ^①	0	1	0	0	0	0	0	R
REG7	0x64	NAME	Reserved	Reserved	VSET[5]	VSET[4]	VSET[3]	VSET[2]	VSET[1]	VSET[0]
		DEFAULT ^①	0	0	1	1	1	0	0	1
REG7	0x65	NAME	ON	DIS	LOWIQ	DELAY[2] ^②	DELAY[1] ^②	DELAY[0] ^②	nFLTMSK	OK
		DEFAULT ^①	0	1	0	0	0	0	0	R

①: Default values of ACT8896Q41133-T.

②: Regulator turn-on delay bits. Automatically cleared to default values when the input power is removed or falls below the system UVLO.

REGISTER AND BIT DESCRIPTIONS

Table 1:
Global Register Map

OUTPUT	ADDRESS	BIT	NAME	ACCESS	DESCRIPTION
SYS	0x00	[7]	TRST	R/W	Reset Timer Setting. Defines the reset time-out threshold. Reset time-out is 65ms when value is 1, reset time-out is 260ms when value is 0. See <i>nRSTO Output</i> section for more information.
SYS	0x00	[6]	nSYSMODE	R/W	SYSLEV Mode Select. Defines the response to the SYSLEV voltage detector, 1: Generate an interrupt when V _{VDDREF} falls below the programmed SYSLEV threshold, 0: automatic shutdown when V _{VDDREF} falls below the programmed SYSLEV threshold.
SYS	0x00	[5]	nSYSLEVMSK	R/W	System Voltage Level Interrupt Mask. Disabled interrupt by default, set to 1 to enable this interrupt. See the <i>Programmable System Voltage Monitor</i> section for more information
SYS	0x00	[4]	nSYSSTAT	R	System Voltage Status. Value is 1 when V _{VDDREF} is lower than the SYSLEV voltage threshold, value is 0 when V _{VDDREF} is higher than the system voltage detection threshold.
SYS	0x00	[3:0]	SYSLEV	R/W	System Voltage Detect Threshold. Defines the SYSLEV voltage threshold. See the <i>Programmable System Voltage Monitor</i> section for more information.
SYS	0x01	[7:4]	-	R	Reserved.
SYS	0x01	[3:0]	SCRATCH	R/W	Scratchpad Bits. Non-functional bits, maybe be used by user to store system status information. Volatile bits, which are cleared upon system shutdown.
REG1	0x20	[7:6]	-	R	Reserved.
REG1	0x20	[5:0]	VSET1	R/W	Primary Output Voltage Selection. Valid when VSEL is driven low. See the <i>Output Voltage Programming</i> section for more information.
REG1	0x21	[7:6]	-	R	Reserved.
REG1	0x21	[5:0]	VSET2	R/W	Secondary Output Voltage Selection. Valid when VSEL is driven high. See the <i>Output Voltage Programming</i> section for more information.
REG1	0x22	[7]	ON	R/W	Regulator Enable Bit. Set bit to 1 to enable the regulator, clear bit to 0 to disable the regulator.
REG1	0x22	[6]	PHASE	R/W	Regulator Phase Control. Set bit to 1 for regulator to operate 180° out of phase with the oscillator, clear bit to 0 for regulator to operate in phase with the oscillator.
REG1	0x22	[5]	MODE	R/W	Regulator Mode Select. Set bit to 1 for fixed-frequency PWM under all load conditions, clear bit to 0 to transit to power-savings mode under light-load conditions.
REG1	0x22	[4:2]	DELAY	R/W	Regulator Turn-On Delay Control. See the <i>REG1, REG2, REG3 Turn-on Delay</i> section for more information.
REG1	0x22	[1]	nFLTMSK	R/W	Regulator Fault Mask Control. Set bit to 1 enable to fault-interrupts, clear bit to 0 to disable fault-interrupts.
REG1	0x22	[0]	OK	R/W	Regulator Power-OK Status. Value is 1 when output voltage exceeds the power-OK threshold, value is 0 otherwise.
REG2	0x30	[7:6]	-	R	Reserved.
REG2	0x30	[5:0]	VSET1	R/W	Primary Output Voltage Selection. Valid when VSEL is driven low. See the <i>Output Voltage Programming</i> section for more information.
REG2	0x31	[7:6]	-	R	Reserved.

REGISTER AND BIT DESCRIPTIONS CONT'D

OUTPUT	ADDRESS	BIT	NAME	ACCESS	DESCRIPTION
REG2	0x31	[5:0]	VSET2	R/W	Secondary Output Voltage Selection. Valid when VSEL is driven high. See the <i>Output Voltage Programming</i> section for more information.
REG2	0x32	[7]	ON	R/W	Regulator Enable Bit. Set bit to 1 to enable the regulator, clear bit to 0 to disable the regulator.
REG2	0x32	[6]	PHASE	R/W	Regulator Phase Control. Set bit to 1 for regulator to operate 180° out of phase with the oscillator, clear bit to 0 for regulator to operate in phase with the oscillator.
REG2	0x32	[5]	MODE	R/W	Regulator Mode Select. Set bit to 1 for fixed-frequency PWM under all load conditions, clear bit to 0 to transit to power-savings mode under light-load conditions.
REG2	0x32	[4:2]	DELAY	R/W	Regulator Turn-On Delay Control. See the <i>REG1, REG2, REG3 Turn-on Delay</i> section for more information.
REG2	0x32	[1]	nFLTMSK	R/W	Regulator Fault Mask Control. Set bit to 1 enable to fault-interrupts, clear bit to 0 to disable fault-interrupts.
REG2	0x32	[0]	OK	R/W	Regulator Power-OK Status. Value is 1 when output voltage exceeds the power-OK threshold, value is 0 otherwise.
REG3	0x40	[7:6]	-	R	Reserved.
REG3	0x40	[5:0]	VSET1	R/W	Primary Output Voltage Selection. Valid when VSEL is driven low. See the <i>Output Voltage Programming</i> section for more information.
REG3	0x41	[7:6]	-	R	Reserved.
REG3	0x41	[5:0]	VSET2	R/W	Secondary Output Voltage Selection. Valid when VSEL is driven high. See the <i>Output Voltage Programming</i> section for more information.
REG3	0x42	[7]	ON	R/W	Regulator Enable Bit. Set bit to 1 to enable the regulator, clear bit to 0 to disable the regulator.
REG3	0x42	[6]	PWRSTAT	R/W	Configures regulator behavior with respect to the nPBIN input. Set bit to 0 to enable regulator when nPBIN is asserted.
REG3	0x42	[5]	MODE	R/W	Regulator Mode Select. Set bit to 1 for fixed-frequency PWM under all load conditions, clear bit to 0 to transition to power-savings mode under light-load conditions.
REG3	0x42	[4:2]	DELAY	R/W	Regulator Turn-On Delay Control. See the <i>REG1, REG2, REG3 Turn-on Delay</i> section for more information.
REG3	0x42	[1]	nFLTMSK	R/W	Regulator Fault Mask Control. Set bit to 1 enable to fault-interrupts, clear bit to 0 to disable fault-interrupts.
REG3	0x42	[0]	OK	R/W	Regulator Power-OK Status. Value is 1 when output voltage exceeds the power-OK threshold, value is 0 otherwise.
REG4	0x50	[7:6]	-	R	Reserved.
REG4	0x50	[5:0]	VSET	R/W	Output Voltage Selection. See the <i>Output Voltage Programming</i> section for more information.
REG4	0x51	[7]	ON	R/W	Regulator Enable Bit. Set bit to 1 to enable the regulator, clear bit to 0 to disable the regulator.
REG4	0x51	[6]	DIS	R/W	Output Discharge Control. When activated, discharges LDO output to GA through 1.5kΩ when in shutdown. Set bit to 1 to enable output voltage discharge in shutdown, clear bit to 0 to disable this function.
REG4	0x51	[5]	LOWIQ	R/W	LDO Low-IQ Mode Control. Set bit to 1 for low-power operating mode, clear bit to 0 for normal mode.
REG4	0x51	[4:2]	DELAY	R/W	Regulator Turn-On Delay Control. See the <i>REG4, REG5, REG6, REG7 Turn-on Delay</i> section for more information.
REG4	0x51	[1]	nFLTMSK	R/W	Regulator Fault Mask Control. Set bit to 1 enable to fault-interrupts, clear bit to 0 to disable fault-interrupts.

REGISTER AND BIT DESCRIPTIONS CONT'D

OUTPUT	ADDRESS	BIT	NAME	ACCESS	DESCRIPTION
REG4	0x51	[0]	OK	R/W	Regulator Power-OK Status. Value is 1 when output voltage exceeds the power-OK threshold, value is 0 otherwise.
REG5	0x54	[7:6]	-	R	Reserved.
REG5	0x54	[5:0]	VSET	R/W	Output Voltage Selection. See the <i>Output Voltage Programming</i> section for more information.
REG5	0x55	[7]	ON	R/W	Regulator Enable Bit. Set bit to 1 to enable the regulator, clear bit to 0 to disable the regulator.
REG5	0x55	[6]	DIS	R/W	Output Discharge Control. When activated, discharges LDO output to GA through 1.5kΩ when in shutdown. Set bit to 1 to enable output voltage discharge in shutdown, clear bit to 0 to disable this function.
REG5	0x55	[5]	LOWIQ	R/W	LDO Low-IQ Mode Control. Set bit to 1 for low-power operating mode, clear bit to 0 for normal mode.
REG5	0x55	[4:2]	DELAY	R/W	Regulator Turn-On Delay Control. See the <i>REG4, REG5, REG6, REG7 Turn-on Delay</i> section for more information.
REG5	0x55	[1]	nFLTMSK	R/W	Regulator Fault Mask Control. Set bit to 1 enable to fault-interrupts, clear bit to 0 to disable fault-interrupts.
REG5	0x55	[0]	OK	R/W	Regulator Power-OK Status. Value is 1 when output voltage exceeds the power-OK threshold, value is 0 otherwise.
REG6	0x60	[7:6]	-	R	Reserved.
REG6	0x60	[5:0]	VSET	R/W	Output Voltage Selection. See the <i>Output Voltage Programming</i> section for more information.
REG6	0x61	[7]	ON	R/W	Regulator Enable Bit. Set bit to 1 to enable the regulator, clear bit to 0 to disable the regulator.
REG6	0x61	[6]	DIS	R/W	Output Discharge Control. When activated, discharges LDO output to GA through 1.5kΩ when in shutdown. Set bit to 1 to enable output voltage discharge in shutdown, clear bit to 0 to disable this function.
REG6	0x61	[5]	LOWIQ	R/W	LDO Low-IQ Mode Control. Set bit to 1 for low-power operating mode, clear bit to 0 for normal mode.
REG6	0x61	[4:2]	DELAY	R/W	Regulator Turn-On Delay Control. See the <i>REG4, REG5, REG6, REG7 Turn-on Delay</i> section for more information.
REG6	0x61	[1]	nFLTMSK	R/W	Regulator Fault Mask Control. Set bit to 1 enable to fault-interrupts, clear bit to 0 to disable fault-interrupts.
REG6	0x61	[0]	OK	R/W	Regulator Power-OK Status. Value is 1 when output voltage exceeds the power-OK threshold, value is 0 otherwise.
REG7	0x64	[7:6]	-	R	Reserved.
REG7	0x64	[5:0]	VSET	R/W	Output Voltage Selection. See the <i>Output Voltage Programming</i> section for more information.
REG7	0x65	[7]	ON	R/W	Regulator Enable Bit. Set bit to 1 to enable the regulator, clear bit to 0 to disable the regulator.
REG7	0x65	[6]	DIS	R/W	Output Discharge Control. When activated, discharges LDO output to GA through 1.5kΩ when in shutdown. Set bit to 1 to enable output voltage discharge in shutdown, clear bit to 0 to disable this function.
REG7	0x65	[5]	LOWIQ	R/W	LDO Low-IQ Mode Control. Set bit to 1 for low-power operating mode, clear bit to 0 for normal mode.
REG7	0x65	[4:2]	DELAY	R/W	Regulator Turn-On Delay Control. See the <i>REG4, REG5, REG6, REG7 Turn-on Delay</i> section for more information.
REG7	0x65	[1]	nFLTMSK	R/W	Regulator Fault Mask Control. Set bit to 1 enable to fault-interrupts, clear bit to 0 to disable fault-interrupts.
REG7	0x65	[0]	OK	R/W	Regulator Power-OK Status. Value is 1 when output voltage exceeds the power-OK threshold, value is 0 otherwise.

SYSTEM CONTROL ELECTRICAL CHARACTERISTICS

($V_{VP1} = V_{VP2} = V_{VP3} = 3.6V$, $T_A = 25^\circ C$, unless otherwise specified.)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Input Voltage Range		2.7		5.5	V
UVLO Threshold Voltage	V_{VDDREF} Rising	2.2	2.45	2.65	V
UVLO Hysteresis	V_{VDDREF} Falling		200		mV
Supply Current	REG1 and REG5 Enabled. REG2, REG3, REG4, REG6 and REG7 Disabled		185		μA
	REG1, REG2, REG3, REG4 and REG5 Enabled. REG6 and REG7 Disabled		350		
	REG1, REG2, REG3, REG4, REG5, REG6 and REG7 Enabled		420		
Shutdown Supply Current	All Regulators Disabled		1.5	3.0	μA
Oscillator Frequency		1.8	2	2.2	MHz
Logic High Input Voltage ^①		1.4			V
Logic Low Input Voltage				0.4	V
Leakage Current	$V_{nIRQ} = V_{nRSTO} = 4.2V$			1	μA
Low Level Output Voltage ^②	$I_{SINK} = 5mA$			0.35	V
nRSTO Delay			260 ^③		ms
Thermal Shutdown Temperature	Temperature rising		160		$^\circ C$
Thermal Shutdown Hysteresis			20		$^\circ C$

①: PWRHLD, PWREN, VSEL are logic inputs.

②: nPBSTAT, nIRQ, nRSTO are open drain outputs.

③: Typical value shown. Actual value may vary from 227.9ms to 291.2ms.

STEP-DOWN DC/DC ELECTRICAL CHARACTERISTICS

($V_{VP1} = V_{VP2} = V_{VP3} = 3.6V$, $T_A = 25^\circ C$, unless otherwise specified.)

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
Operating Voltage Range		2.7		5.5	V
UVLO Threshold	Input Voltage Rising	2.5	2.6	2.7	V
UVLO Hysteresis	Input Voltage Falling		100		mV
Quiescent Supply Current	Regulator Enabled		65	90	μA
Shutdown Current	$V_{VP} = 5.5V$, Regulator Disabled		0	1	μA
Output Voltage Accuracy	$V_{OUT} \geq 1.2V$, $I_{OUT} = 10mA$	-1%	$V_{NOM}^{\textcircled{1}}$	1%	V
	$V_{OUT} < 1.2V$, $I_{OUT} = 10mA$	-2%	$V_{NOM}^{\textcircled{1}}$	2%	
Line Regulation	$V_{VP} = \text{Max}(V_{NOM}^{\textcircled{1}} + 1, 3.2V)$ to 5.5V		0.15		%/V
Load Regulation	$I_{OUT} = 10mA$ to $I_{MAX}^{\textcircled{2}}$		0.0017		%/mA
Power Good Threshold	V_{OUT} Rising		93		% V_{NOM}
Power Good Hysteresis	V_{OUT} Falling		2		% V_{NOM}
Oscillator Frequency	$V_{OUT} \geq 20\%$ of V_{NOM}	1.8	2	2.2	MHz
	$V_{OUT} = 0V$		500		kHz
Soft-Start Period			400		μs
Minimum On-Time			75		ns
REG1					
Maximum Output Current		0.9			A
Current Limit		1.2	1.4	1.7	A
PMOS On-Resistance	$I_{SW1} = -100mA$		0.18		Ω
NMOS On-Resistance	$I_{SW1} = 100mA$		0.16		Ω
SW1 Leakage Current	$V_{VP1} = 5.5V$, $V_{SW1} = 0$ or 5.5V		0	1	μA
REG2					
Maximum Output Current		0.7			A
Current Limit		0.9	1.1	1.3	A
PMOS On-Resistance	$I_{SW2} = -100mA$		0.21		Ω
NMOS On-Resistance	$I_{SW2} = 100mA$		0.16		Ω
SW2 Leakage Current	$V_{VP2} = 5.5V$, $V_{SW2} = 0$ or 5.5V		0	1	μA
REG3					
Maximum Output Current		0.9			A
Current Limit		1.2	1.4	1.7	A
PMOS On-Resistance	$I_{SW3} = -100mA$		0.18		Ω
NMOS On-Resistance	$I_{SW3} = 100mA$		0.16		Ω
SW3 Leakage Current	$V_{VP3} = 5.5V$, $V_{SW3} = 0$ or 5.5V		0	1	μA

$\textcircled{1}$: V_{NOM} refers to the nominal output voltage level for V_{OUT} as defined by the *Ordering Information* section.

$\textcircled{2}$: I_{MAX} Maximum Output Current.

LOW-NOISE LDO ELECTRICAL CHARACTERISTICS

($V_{INL} = 3.6V$, $C_{OUT4} = C_{OUT5} = 1.5\mu F$, $C_{OUT6} = C_{OUT7} = 2.2\mu F$, $LOWIQ[] = [0]$, $T_A = 25^\circ C$, unless otherwise specified.)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Operating Voltage Range		2.5		5.5	V
Output Voltage Accuracy	$V_{OUT} \geq 1.2V$, $T_A = 25^\circ C$, $I_{OUT} = 10mA$	-1%	$V_{NOM}^{\textcircled{1}}$	2%	V
	$V_{OUT} < 1.2V$, $T_A = 25^\circ C$, $I_{OUT} = 10mA$	-2%	$V_{NOM}^{\textcircled{1}}$	4%	
Line Regulation	$V_{INL} = \text{Max}(V_{OUT} + 0.5V, 3.6V)$ to 5.5V $LOWIQ[] = [0]$		0.05		mV/V
	$V_{INL} = \text{Max}(V_{OUT} + 0.5V, 3.6V)$ to 5.5V $LOWIQ[] = [1]$		0.5		
Load Regulation	$I_{OUT} = 1mA$ to $IMAX^{\textcircled{2}}$		0.08		V/A
Power Supply Rejection Ratio	$f = 1kHz$, $I_{OUT} = 20mA$, $V_{OUT} = 1.2V$		75		dB
	$f = 10kHz$, $I_{OUT} = 20mA$, $V_{OUT} = 1.2V$		65		
Supply Current per Output	Regulator Enabled, $LOWIQ[] = [0]$		37	60	μA
	Regulator Enabled, $LOWIQ[] = [1]$		31	52	
	Regulator Disabled		0	1	
Soft-Start Period	$V_{OUT} = 2.9V$		140		μs
Power Good Threshold	V_{OUT} Rising		89		%
Power Good Hysteresis	V_{OUT} Falling		3		%
Output Noise	$I_{OUT} = 20mA$, $f = 10Hz$ to $100kHz$, $V_{OUT} = 1.2V$		50		μV_{RMS}
Discharge Resistance	LDO Disabled, $DIS[] = 1$		1.5		$k\Omega$
REG4					
Dropout Voltage ^③	$I_{OUT} = 80mA$, $V_{OUT} > 3.1V$		90	180	mV
Maximum Output Current		150			mA
Current Limit ^④	$V_{OUT} = 95\%$ of regulation voltage	200			mA
Stable C_{OUT4} Range		1.5		20	μF
REG5					
Dropout Voltage	$I_{OUT} = 80mA$, $V_{OUT} > 3.1V$		140	280	mV
Maximum Output Current		150			mA
Current Limit	$V_{OUT} = 95\%$ of regulation voltage	200			mA
Stable C_{OUT5} Range		1.5		20	μF
REG6					
Dropout Voltage	$I_{OUT} = 120mA$, $V_{OUT} > 3.1V$		90	180	mV
Maximum Output Current		250			mA
Current Limit	$V_{OUT} = 95\%$ of regulation voltage	300			mA
Stable C_{OUT6} Range		2.2		20	μF
REG7					
Dropout Voltage	$I_{OUT} = 120mA$, $V_{OUT} > 3.1V$		140	280	mV
Maximum Output Current		250			mA
Current Limit	$V_{OUT} = 95\%$ of regulation voltage	300			mA
Stable C_{OUT7} Range		2.2		20	μF

①: V_{NOM} refers to the nominal output voltage level for V_{OUT} as defined by the *Ordering Information* section.

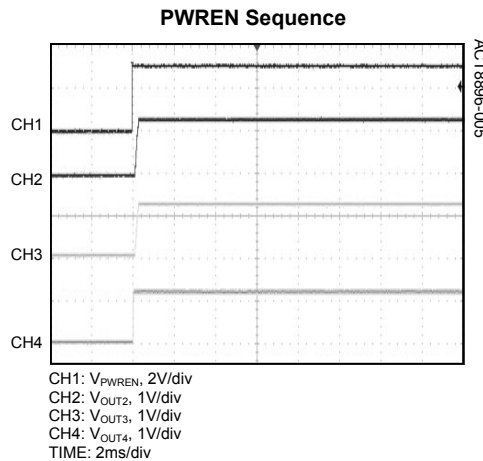
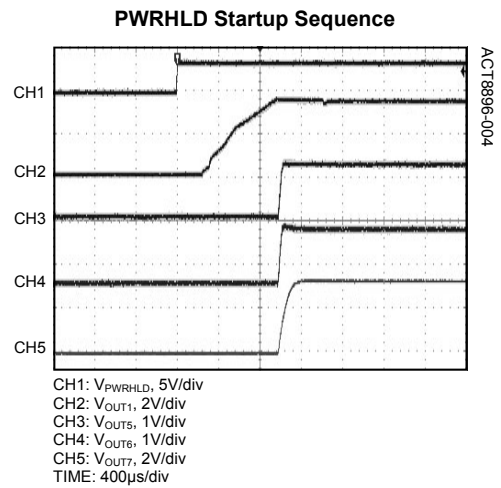
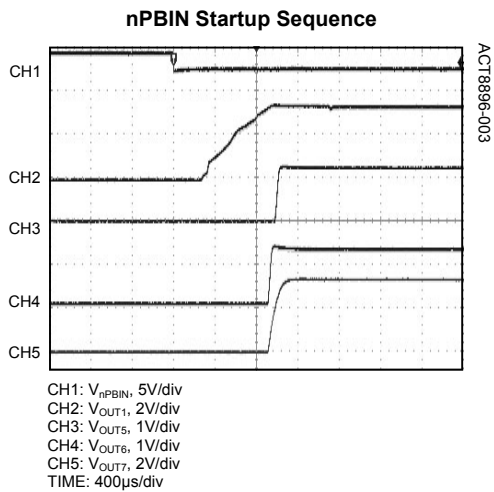
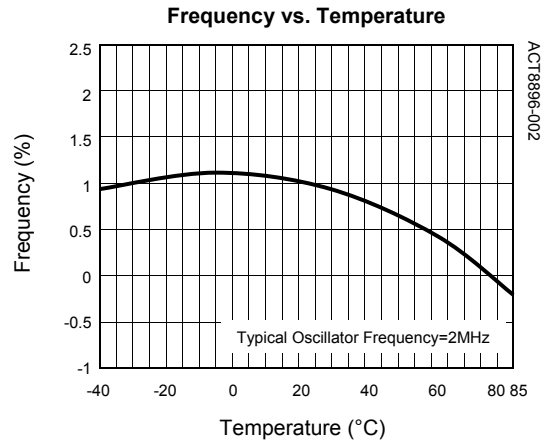
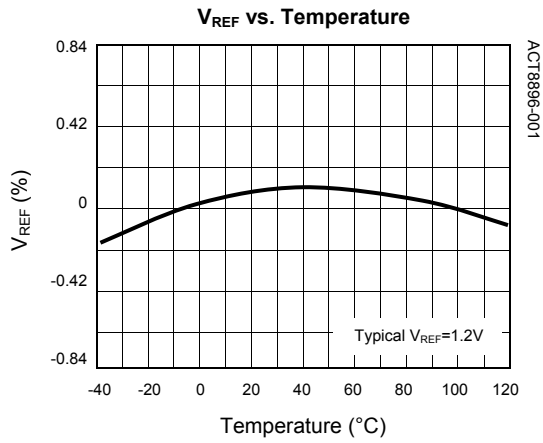
②: $IMAX$ Maximum Output Current.

③: Dropout Voltage is defined as the differential voltage between input and output when the output voltage drops 100mV below the regulation voltage (for 3.1V output voltage or higher)

④: LDO current limit is defined as the output current at which the output voltage drops to 95% of the respective regulation voltage. Under heavy overload conditions the output current limit folds back by 30% (typ)

TYPICAL PERFORMANCE CHARACTERISTICS

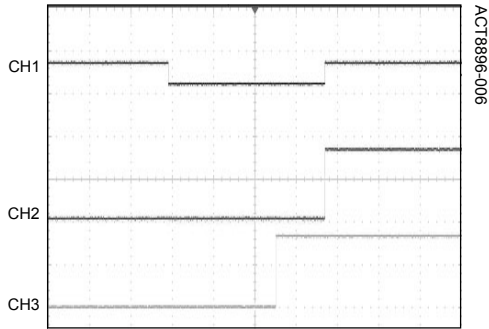
($V_{VP1} = V_{VP2} = V_{VP3} = 3.6V$, $T_A = 25^\circ C$, unless otherwise specified.)



TYPICAL PERFORMANCE CHARACTERISTICS CONT'D

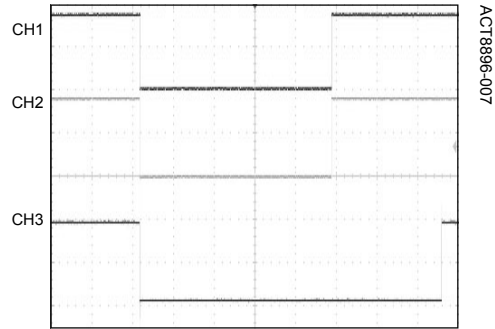
($T_A = 25^\circ\text{C}$, unless otherwise specified.)

Push-Button Response (First Power-Up)



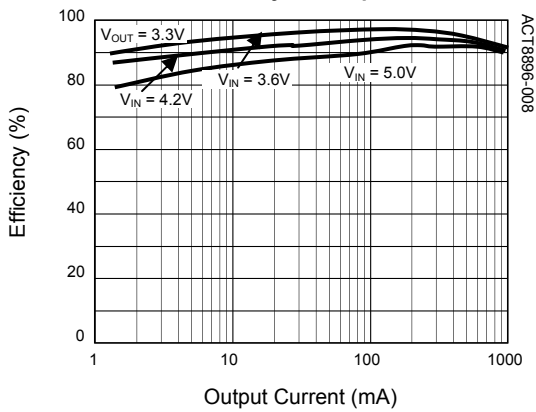
CH1: V_{nPBIN} , 2V/div
CH2: $V_{nPBSTAT}$, 2V/div
CH3: V_{nRSTO} , 2V/div
TIME: 100ms/div
nPBIN Resistor = 50k Ω

Manual Reset Response

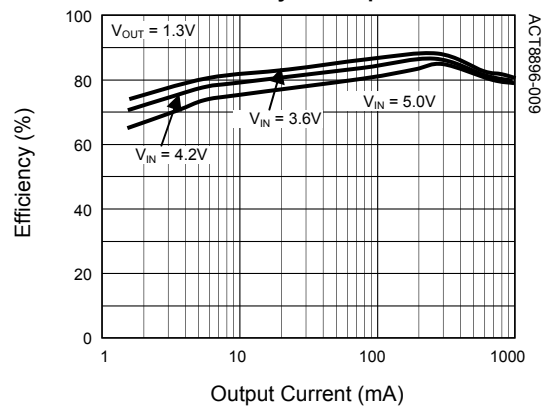


CH1: V_{nPBIN} , 2V/div
CH2: $V_{nPBSTAT}$, 2V/div
CH3: V_{nRSTO} , 2V/div
TIME: 100ms/div
nPBIN Resistor = 0 Ω

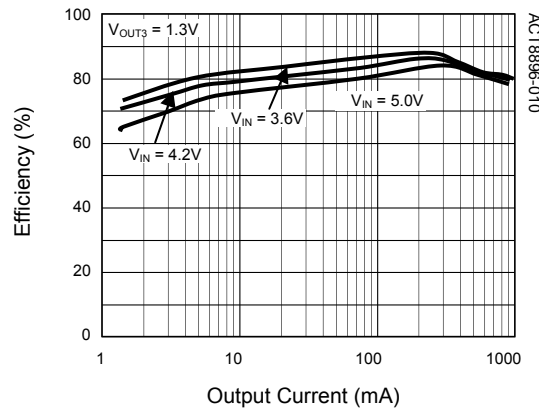
REG1 Efficiency vs. Output Current



REG2 Efficiency vs. Output Current

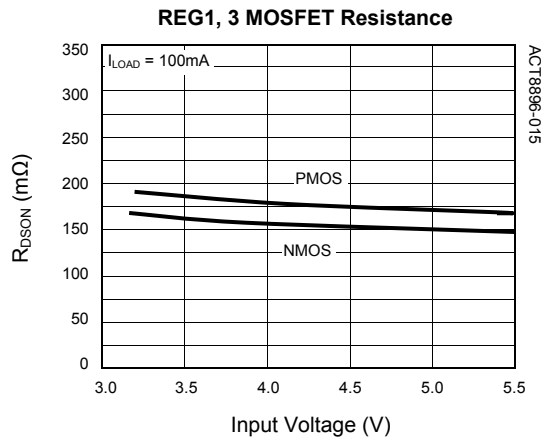
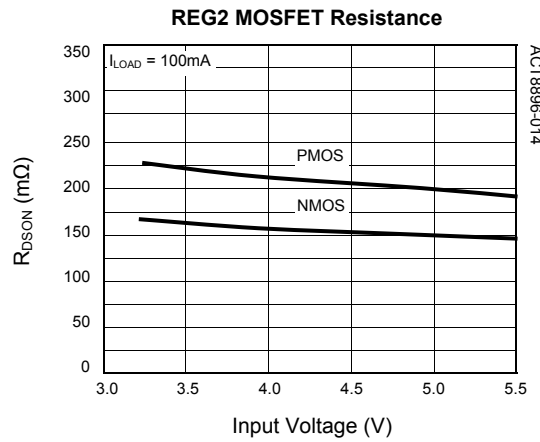
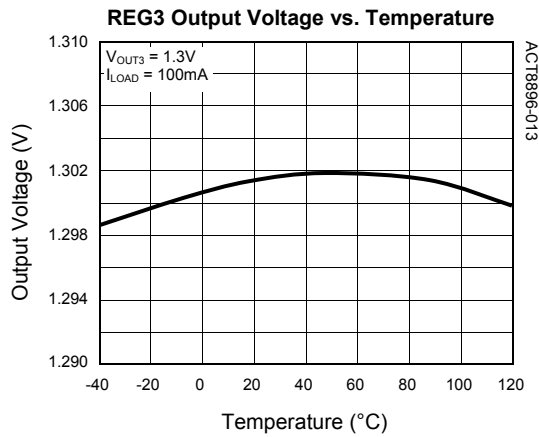
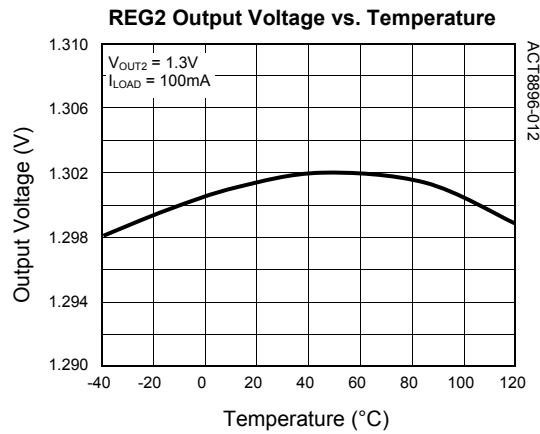
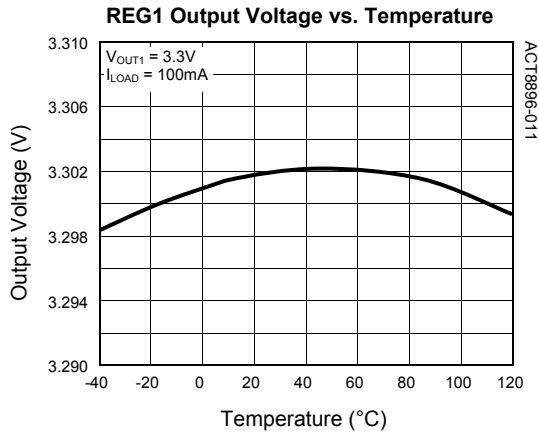


REG3 Efficiency vs. Output Current



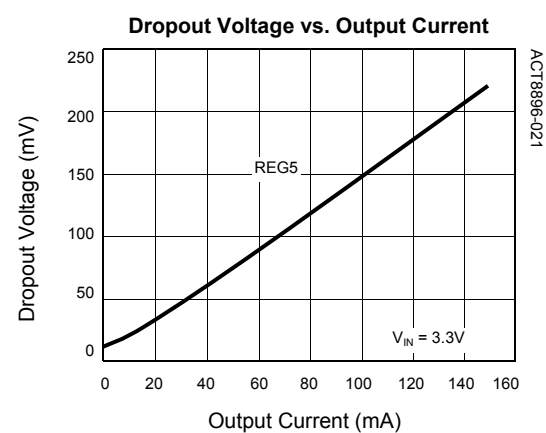
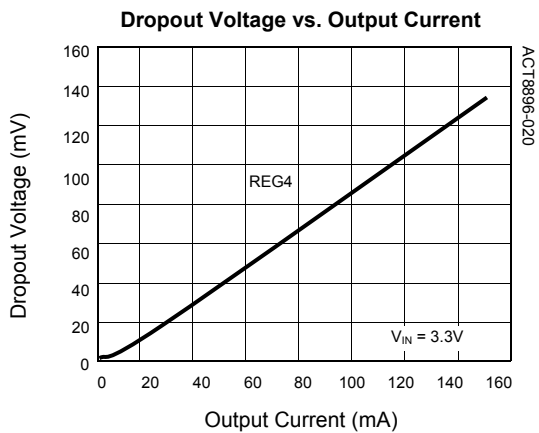
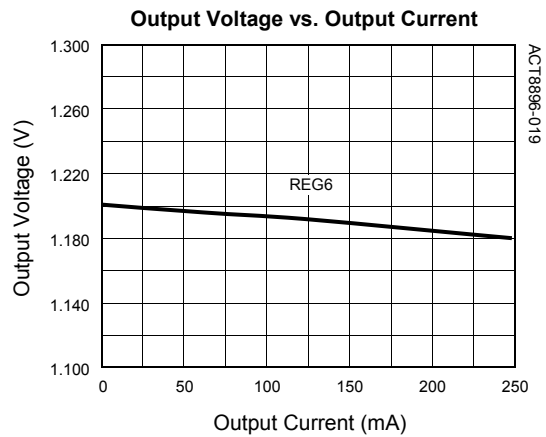
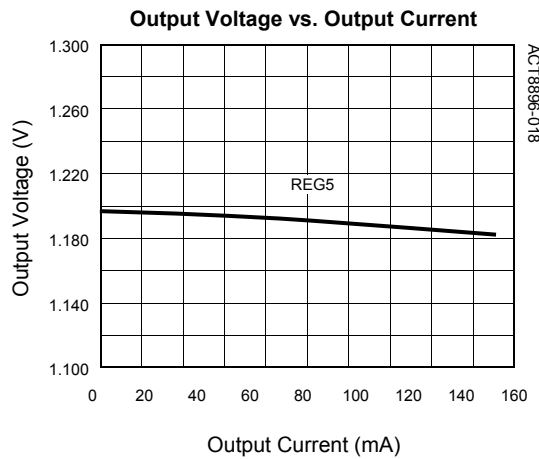
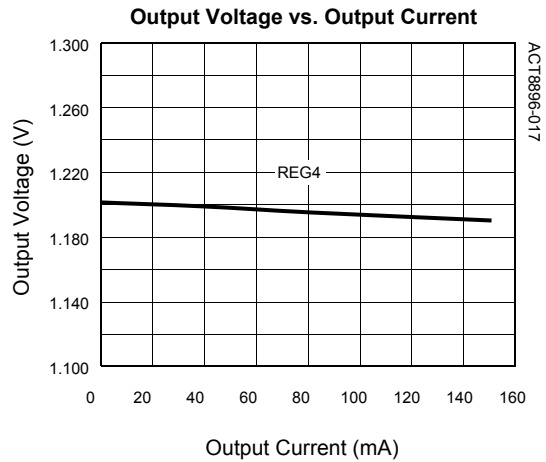
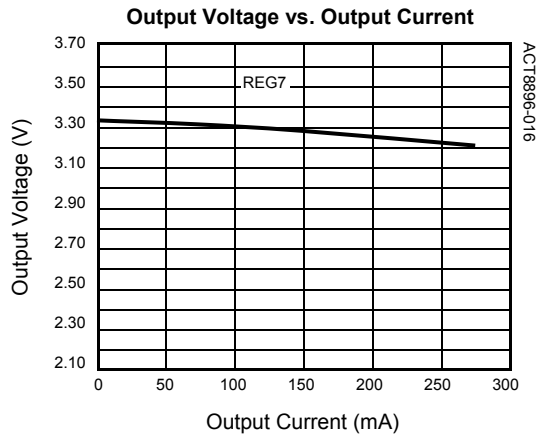
TYPICAL PERFORMANCE CHARACTERISTICS CONT'D

($T_A = 25^\circ\text{C}$, unless otherwise specified.)



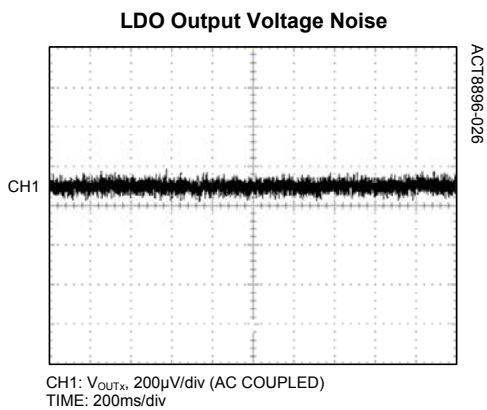
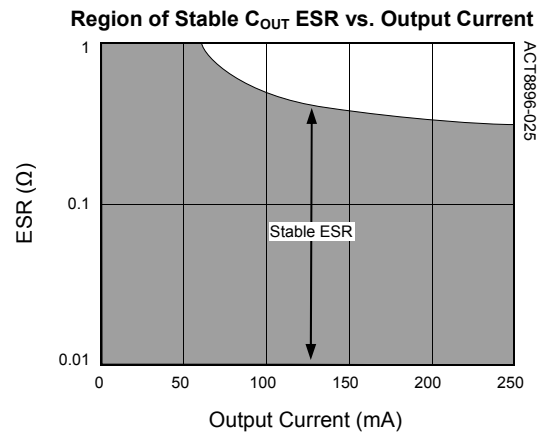
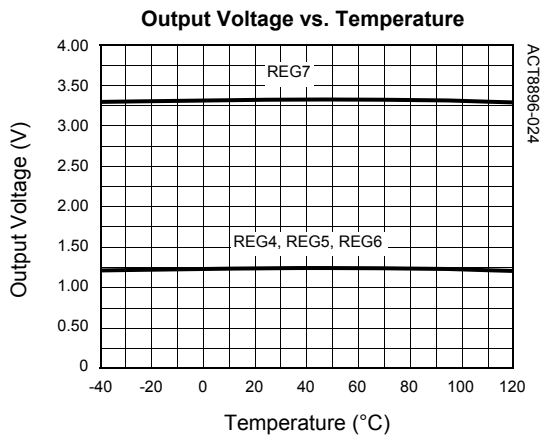
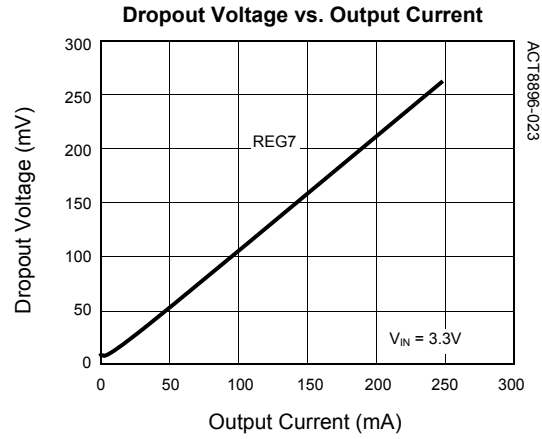
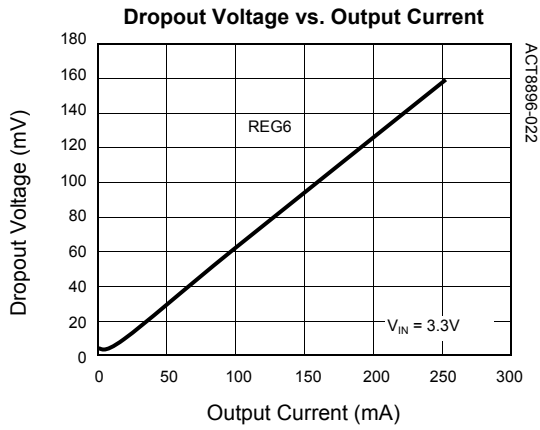
TYPICAL PERFORMANCE CHARACTERISTICS CONT'D

($T_A = 25^\circ\text{C}$, unless otherwise specified.)



TYPICAL PERFORMANCE CHARACTERISTICS CONT'D

($T_A = 25^\circ\text{C}$, unless otherwise specified.)



SYSTEM CONTROL INFORMATION

Interfacing with the Samsung S3C6410

The ACT8896 is optimized for use in applications using the S3C6410 processor, supporting both the power domains as well as the signal interface for these processors.

While the ACT8896 supports many possible configurations for powering these processors, one of the most common configurations is detailed in this datasheet. In general, this document refers to the ACT8896 pin names and functions. However, in cases where the description of interconnections between these devices benefits by doing so, both

the ACT8896 pin names and the Samsung processor pin names are provided. When this is done, the S3C6410 pin names are located after the ACT8896 pin names, and are italicized and located inside parentheses. For example, PWREN (*XPWRRGTON*) refers to the logic signal applied to the ACT8896's PWREN input, identifying that it is driven from the S3C6410's XPWRRGTON output. Likewise, OUT1 (*VDD_IO*) refers to ACT8896's OUT1 pin, identifying that it is connected to the S3C6410's VDD_IO power domain.

Table 2:
ACT8896 and Samsung S3C6410 Power Domains

POWER DOMAIN	ACT8896 CHANNEL	TYPE	DEFAULT VOLTAGE	CURRENT CAPABILITY
VDD_IO	REG1	DC/DC	3.3V/3.3V	900mA
VDD_INT	REG2	DC/DC	1.3V/1.3V	700mA
VDD_ARM	REG3	DC/DC	1.3V/1.3V	900mA
VDD_xPLL	REG4	LDO	1.2V	150mA
VDD_Alive	REG5	LDO	1.2V	150mA
VDD12_UOTG	REG6	LDO	1.2V	250mA
VDD33_UOTG	REG7	LDO	3.3V	250mA

Table 3:
ACT8896 and Samsung S3C6410 Power Modes

POWER MODE	CONTROL STATE	POWER DOMAIN STATE	QUIESCENT CURRENT
ALL ON	PWRHLD is asserted, PWREN is asserted	REG1, REG2, REG3, REG4, REG5, REG6 and REG7 are all on	420µA
NORMAL	PWRHLD is asserted, PWREN is asserted, REG6 and REG7 are disabled by I ² C	REG1, REG2, REG3, REG4 and REG5 are on. REG6 and REG7 are off	350µA
SLEEP	PWRHLD is asserted, PWREN is de-asserted, REG6 and REG7 are disabled by I ² C	REG1 and REG5 are on. REG2, REG3, REG4, REG6 and REG7 are off	185µA
ALL OFF	PWRHLD is de-asserted, PWREN is de-asserted	REG1, REG2, REG3, REG4, REG5, REG6 and REG7 are all off	<18µA

Table 4:
ACT8896 and Samsung S3C6410 Signal Interface

ACT8896	DIRECTION	SAMSUNG S3C6410
PWREN	←	XPWRRGTON
SCL	←	Xi2cSCL[0]
SDA	↔	Xi2cSDA[0]
VSEL	←	DVS_GPIO ^①
nRSTO	→	XnRESET
nIRQ	→	XEINT0 ^②
nPBSTAT	→	XEINT1 ^③
PWRHLD	←	Power hold GPIO ^④

- ①: Optional connection for DVS control.
- ②, ③: Typical connections shown, actual connections may vary.
- ④: Optional connection for power hold control.

Table 5:
Control Pins

PIN NAME	OUTPUT
nPBIN	REG1, REG5, REG6, REG7
PWRHLD	REG1, REG5, REG6, REG7
PWREN	REG2, REG3, REG4

Control Signals

Enable Inputs

The ACT8896 features a variety of control inputs, which are used to enable and disable outputs depending upon the desired mode of operation. PWREN, PWRHLD are logic inputs, while nPBIN is a unique, multi-function input. Refer to Table 5 for a description of which channels are controlled by each input.

nPBIN Multi-Function Input

ACT8896 features the nPBIN multi-function pin, which combines system enable/disable control with a hardware reset function. Select either of the two pin functions by asserting this pin, either through a direct connection to GA, or through a 50kΩ resistor to GA, as shown in Figure 2.

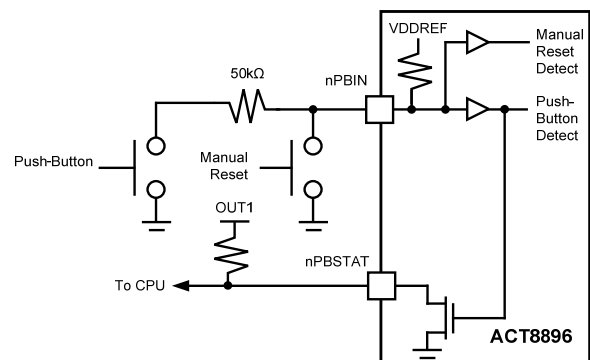
Manual Reset Function

The second major function of the nPBIN input is to provide a manual-reset input for the processor. To manually-reset the processor, drive nPBIN directly to GA through a low impedance (less than 2.5kΩ). When this occurs, nRSTO immediately asserts low, then remains asserted low until the nPBIN input is de-asserted and the reset timeout period expires.

nPBSTAT Output

nPBSTAT is an open-drain output that reflects the state of the nPBIN input; nPBSTAT is asserted low whenever nPBIN is asserted, and is high-Z otherwise. This output is typically used as an interrupt signal to the processor, to initiate a software-programmable routine such as operating mode selection or to open a menu. Connect nPBSTAT to an appropriate supply voltage (typically OUT1) through a 10kΩ or greater resistor.

Figure 2:
nPBIN Input



nRSTO Output

nRSTO is an open-drain output which asserts low upon startup or when manual reset is asserted via the nPBIN input. When asserted on startup, nRSTO remains low until reset timeout period expires after OUT1 reaches its power-OK threshold. When asserted due to manual-reset, nRSTO immediately asserts low, then remains asserted low until the nPBIN input is de-asserted and the reset timeout period expires.

Connect a 10kΩ or greater pull-up resistor from nRSTO to an appropriate voltage supply (typically OUT1).

nIRQ Output

nIRQ is an open-drain output that asserts low any time an interrupt is generated. Connect a 10kΩ or greater pull-up resistor from nIRQ to an appropriate voltage supply. nIRQ is typically used to drive the interrupt input of the system processor.

Many of the ACT8896's functions support interrupt-generation as a result of various conditions. These are typically masked by default, but may be unmasked via the I²C interface. For more information about the available fault conditions, refer to the appropriate sections of this datasheet.

Note that under some conditions a false interrupt may be generated upon initial startup. For this reason, it is recommended that the interrupt service routine check and validate nSYSLEVMSK[] and nFLTMSK[] bits before processing an interrupt generated by these bits. These interrupts may be validated by nSYSSTAT[], OK[] bits.

Push-Button Control

The ACT8896 is designed to initiate a system enable sequence when the nPBIN multi-function input is asserted. Once this occurs, a power-on sequence commences, as described below. The power-on sequence must complete and the microprocessor must take control (by asserting PWREN or PWRHLD) before nPBIN is de-asserted. If the microprocessor is unable to complete its power-up routine successfully before the user lets the push-button go off, the ACT8896 automatically shuts the system down. This provides protection against accidental or momentary assertions of the push-button. If desired, longer "push-and-hold" times can be easily implemented by simply adding an additional time delay before asserting PWREN or PWRHLD.

Control Sequences

The ACT8896 features a variety of control

sequences that are optimized for supporting system enable and disable, as well as SLEEP mode of the Samsung S3C6410 processor.

Enabling/Disabling Sequence

A typical enable sequence initiates as a result of asserting nPBIN, and begins by enabling REG1. When REG1 reaches its power-OK threshold, REG5, REG6 and REG7 are enabled and nRSTO is asserted low, resetting the microprocessor. If REG1 is above its power-OK threshold when the reset timer expires, nRSTO is de-asserted, allowing the microprocessor to begin its boot sequence.

During the boot sequence, the microprocessor must assert PWRHLD, holding REG1, REG5, REG6 and REG7, and assert PWREN (*XPWRRGTON*), enabling REG2, REG3 and REG4 to ensure that the system remains powered after nPBIN is released.

Once the power-up routine is completed, the system remains enabled after the push-button is released as long as either PWRHLD or PWREN are asserted high. If the processor does not assert PWRHLD or PWREN before the user releases the push-button, the boot-up sequence is terminated and all regulators are disabled. This provides protection against "false-enable", when the push-button is accidentally depressed, and also ensures that the system remains enabled only if the processor successfully completes the boot-up sequence.

As with the enable sequence, a typical disable sequence is initiated when the user presses the push-button, which interrupts the processor via the nPBSTAT output. The actual disable sequence is completely software-controlled, but typically involved initiating various "clean-up" processes then finally de-assert PWRHLD and PWREN, disabling all regulators and shutting the system down.

SLEEP Mode Sequence

The ACT8896 supports Samsung S3C6410 Processor's SLEEP mode operation. Once a successful power-up routine has been completed, SLEEP mode may be initiated through a variety of software-controlled mechanisms.

SLEEP mode is typically initiated when the user presses the push-button during normal operation. Pressing the push-button asserts the nPBIN input, which asserts the nPBSTAT output, which interrupts the processor. In response to this interrupt the processor should disable REG6 and REG7 via I²C first, then de-assert PWREN, disabling REG2, REG3, and REG4. PWRHLD should remain asserted during SLEEP mode so that

REG1 and REG5 remain enabled.

Waking from SLEEP mode is initiated when the user presses the push-button again, which enables REG6 and REG7, and asserts nPBSTAT.

Processors should respond by asserting PWREN, which enables REG2, REG3 and REG4 so that normal operation may resume.

Figure 3:
Enable/Disable Sequence

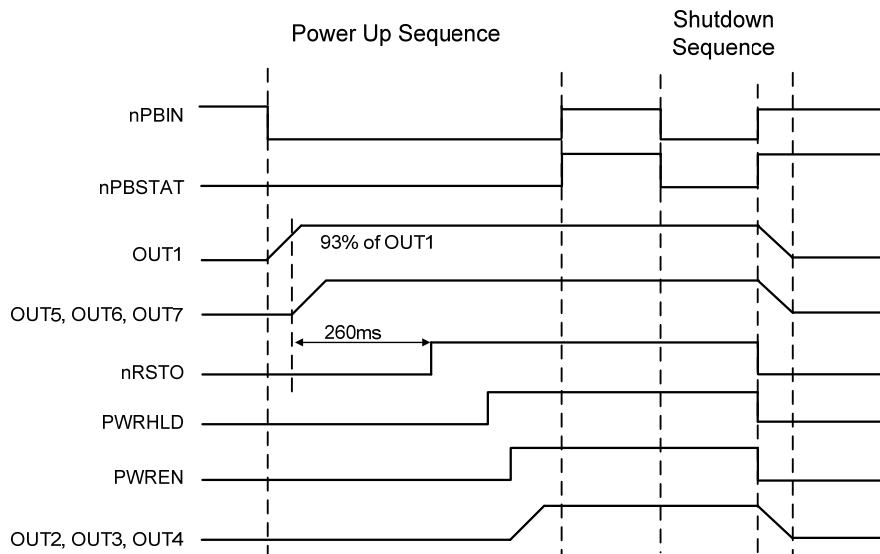
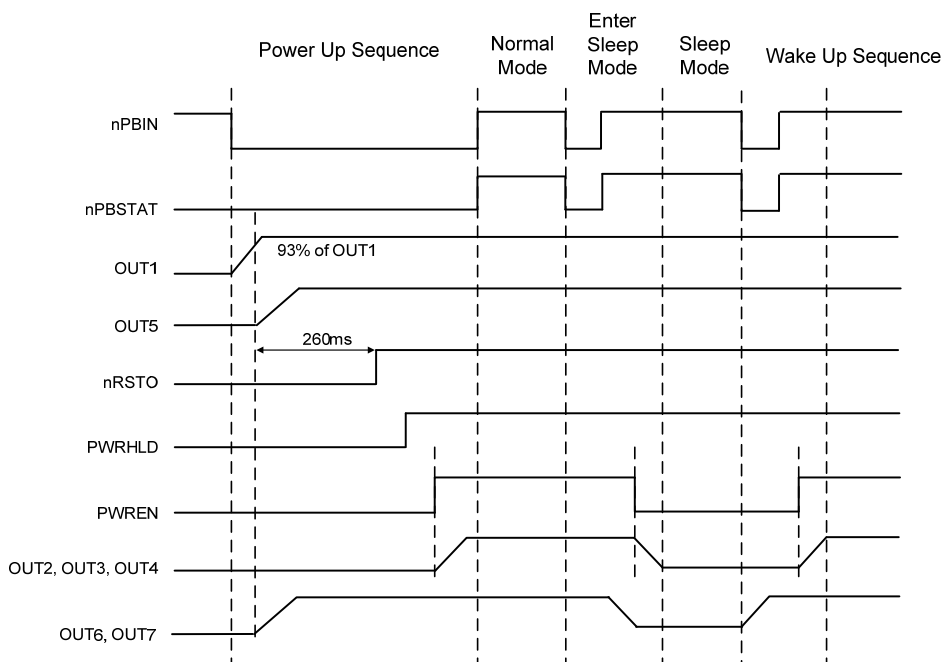


Figure 4:
Sleep Mode Sequence



FUNCTIONAL DESCRIPTION

I²C Interface

The ACT8896 features an I²C interface that allows advanced programming capability to enhance overall system performance. To ensure compatibility with a wide range of system processors, the I²C interface supports clock speeds of up to 400kHz ("Fast-Mode" operation) and uses standard I²C commands. I²C write-byte commands are used to program the ACT8896, and I²C read-byte commands are used to read the ACT8896's internal registers. The ACT8896 always operates as a slave device, and is addressed using a 7-bit slave address followed by an eighth bit, which indicates whether the transaction is a read-operation or a write-operation, [1011011x].

SDA is a bi-directional data line and SCL is a clock input. The master device initiates a transaction by issuing a START condition, defined by SDA transitioning from high to low while SCL is high. Data is transferred in 8-bit packets, beginning with the MSB, and is clocked-in on the rising edge of SCL. Each packet of data is followed by an "Acknowledge" (ACK) bit, used to confirm that the data was transmitted successfully.

For more information regarding the I²C 2-wire serial interface, go to the NXP website: <http://www.nxp.com>.

Voltage Monitor and Interrupt

Programmable System Voltage Monitor

The ACT8896 features a programmable system-voltage monitor, which monitors the voltage at VDDREF and compares it to a programmable threshold voltage. The programmable voltage threshold is programmed by SYSLEV[3:0], as shown in Table 6.

SYSLEV[] is set to 3.0V by default. There is a 200mV rising hysteresis on SYSLEV[] threshold such that VDDREF needs to be 3.2V(typ) or higher in order to power up the IC.

The nSYSSTAT[] bit reflects the output of an internal voltage comparator that monitors VDDREF relative to the SYSLEV[] voltage threshold, the value of nSYSSTAT[] = 1 when VDDREF is lower than the SYSLEV[] voltage threshold, and nSYSSTAT[] = 0 when VDDREF is higher than the SYSLEV[] voltage threshold. Note that the SYSLEV[] voltage threshold is defined for falling voltages, and that the comparator produces about 200mV of hysteresis at VDDREF. As a result, once VDDREF falls below the SYSLEV threshold, its voltage must increase by more than about 200mV to clear that condition.

After the IC is powered up, the ACT8896 responds in one of two ways when the voltage at VDDREF falls

below the SYSLEV[] voltage threshold:

1) If nSYSMODE[] = 1 (default case), when system voltage level interrupt is unmasked (nSYSLEVMASK[]=1) and VDDREF falls below the programmable threshold, the ACT8896 asserts nIRQ, providing a software "under-voltage alarm". The response to this interrupt is controlled by the CPU, but will typically initiate a controlled shutdown sequence either or alert the user that the battery is low. In this case the interrupt is cleared when VDDREF rises up again above the SYSLEV rising threshold and nSYSSTAT[] is read via I²C.

2) If nSYSMODE[] = 0, when VDDREF falls below the programmable threshold the ACT8896 shuts down, immediately disabling all regulators. This option is useful for implementing a programmable "under-voltage lockout" function that forces the system off when the battery voltage falls below the SYSLEV threshold voltage. Since this option does not support a controlled shutdown sequence, it is generally used as a "fail-safe" to shut the system down when the battery voltage is too low.

Table 6:

SYSLEV Falling Threshold

SYSLEV[3:0]	SYSLEV Falling Threshold (Hysteresis = 200mV)
0000	2.3
0001	2.4
0010	2.5
0011	2.6
0100	2.7
0101	2.8
0110	2.9
0111	3.0
1000	3.1
1001	3.2
1010	3.3
1011	3.4
1100	3.5
1101	3.6
1110	3.7
1111	3.8

Thermal Shutdown

The ACT8896 integrates thermal shutdown protection circuitry to prevent damage resulting from excessive thermal stress, as may be encountered under fault conditions. This circuitry disables all regulators if the ACT8896 die temperature exceeds 160°C, and prevents the regulators from being enabled until the IC temperature drops by 20°C (typ).